



Advanced Studies in Solder Joints

Guest Editors:

Dr. Haoran Ma

School of Microelectronics,
Dalian University of Technology,
Dalian, China

Dr. Yi Zhong

School of Electronic Science and
Engineering (National Model
Microelectronics College),
Xiamen University, Xiamen, China

Dr. Anil Kunwar

Faculty of Mechanical
Engineering, Silesian University
of Technology, Konarskiego 18A,
44-100 Gliwice, Poland

Deadline for manuscript
submissions:

31 December 2024

Message from the Guest Editors

Solder joints have been the key structural component in advanced packaging. Following Moore's Law leading the development of chip technology gradually approaching the physical limit in recent years, the realization of "More than Moore" through advanced packaging technology has become the main developing direction of electronic manufacturing. Significant advances in solder joints have been achieved as a result of interdisciplinary research in related fields of materials characterization, mechanical property, microelectronics technology, physics and chemistry, constitutive modeling, mathematical analysis and numerical methods.

This Special Issue on "Advanced Studies in Solder Joints" intends to collect the latest developments in the field, written by well-known researchers who have contributed significantly on at least one of these specific topics - interfacial reaction mechanisms, microstructures and properties characterization, numerical modeling and simulations of solder joints in advanced electronic manufacturing and packaging.





an Open Access Journal by MDPI

Editors-in-Chief

Prof. Dr. Hugo F. Lopez

Department of Materials Science and Engineering, College of Engineering & Applied Science, University of Wisconsin-Milwaukee, 3200 N. Cramer Street, Milwaukee, WI 53211, USA

Prof. Dr. Yong Zhang

Beijing Advanced Innovation Center of Materials Genome Engineering, State Key Laboratory for Advanced Metals and Materials, University of Science and Technology Beijing, 30 Xueyuan Road, Beijing 100083, China

Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (*Metallurgy and Metallurgical Engineering*) / CiteScore - Q1 (Metals and Alloys)

Contact Us

Metals Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/metals
metals@mdpi.com
[X@Metals_MDPI](https://twitter.com/Metals_MDPI)